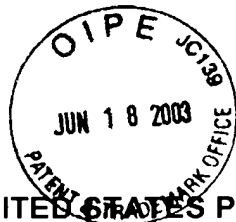


Docket No.: 3008-0028
File No. 521.41457X00
Client No.: PHCF-01094



PATENT

2827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Seigi AOYAMA et al.

Application S/N 09/892,630

Filed: June 28, 2001

: Art Unit: 2827

: Examiner: T. Dinh

For: LEAD-FREE SOLDER, AND CONNECTION LEAD AND ELECTRICAL
COMPONENT USING SAID LEAD-FREE SOLDER

Honorable Assistant Commissioner
for Patents
Washington, DC 20231

Sir:

Transmitted herewith is a Preliminary Amendment in the above-identified application.

☒ No additional fee is required.

☐ Also attached:

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	10	20	0	x \$18 =	\$0
Independent Claims	4	5	0	x \$84 =	\$0
Petition for Extension of Time for ___ month					\$0
TOTAL FEE DUE					\$0

Docket No.: 3008-0028
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PATENT

- ☐ A Credit Card Payment form in the amount of \$_____ is attached
- ☒ Commissioner is hereby authorized to charge any additional fees associated with this communication or credit any overpayment, to Deposit Account No. 01-2135, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully Submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP



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Date: June 18, 2003

Docket No.: 3008-0028
File No. 521,41457X00
Client No.: PHCF-01094



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Seigi AOYAMA et al.

Application S/N 09/892,630

Filed: June 28, 2001

For: LEAD-FREE SOLDER, AND CONNECTION LEAD AN

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: Art Unit: 2827
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: Examiner: T. Dinh
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PRELIMINARY AMENDMENT

Honorable Assistant Commissioner
for Patents
Washington, DC 20231

Sir:

This preliminary amendment is directed to the above-referenced application on which a Request for Continued Examination was filed on May 19, 2003, and further to the Request for Reconsideration filed concurrently with the RCE. Prior to examination, please further amend the application as follows:

IN THE CLAIMS

Please amend the claims to read as follows (see also Appendix of Claim Amendments):

2. (Three Times Amended) A lead-free solder used to connect a connection lead to a material, comprising:

an alloy composition containing 0.002 to 0.015% by mass of phosphorus with the